



Material Content Data Sheet



Sales Product Name		IFX78M05ABTF		Issued		1. August 2018		
MA#		MA001121562						
Package		PG-TO252-3-11		Weight*		376.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.237	0.33	0.33	3283	3283
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		171	
	non noble metal	iron	7439-89-6	0.215	0.06		571	
	non noble metal	copper	7440-50-8	215.017	57.05	57.13	570551	571293
	non noble metal	aluminium	7429-90-5	0.143	0.04	0.04	380	380
wire	non noble metal	aluminium	7429-90-5	0.143	0.04	0.04	380	380
encapsulation	organic material	carbon black	1333-86-4	0.271	0.07		719	
	plastics	epoxy resin	-	12.471	3.31		33093	
	inorganic material	silicondioxide	60676-86-0	122.817	32.59	35.97	325897	359709
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9924	9924
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	241	242
solder	non noble metal	tin	7440-31-5	0.032	0.01		84	
	noble metal	silver	7440-22-4	0.040	0.01		105	
	non noble metal	lead	7439-92-1	1.517	0.40	0.42	4026	4215
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.09	5.10	50888	50954
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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